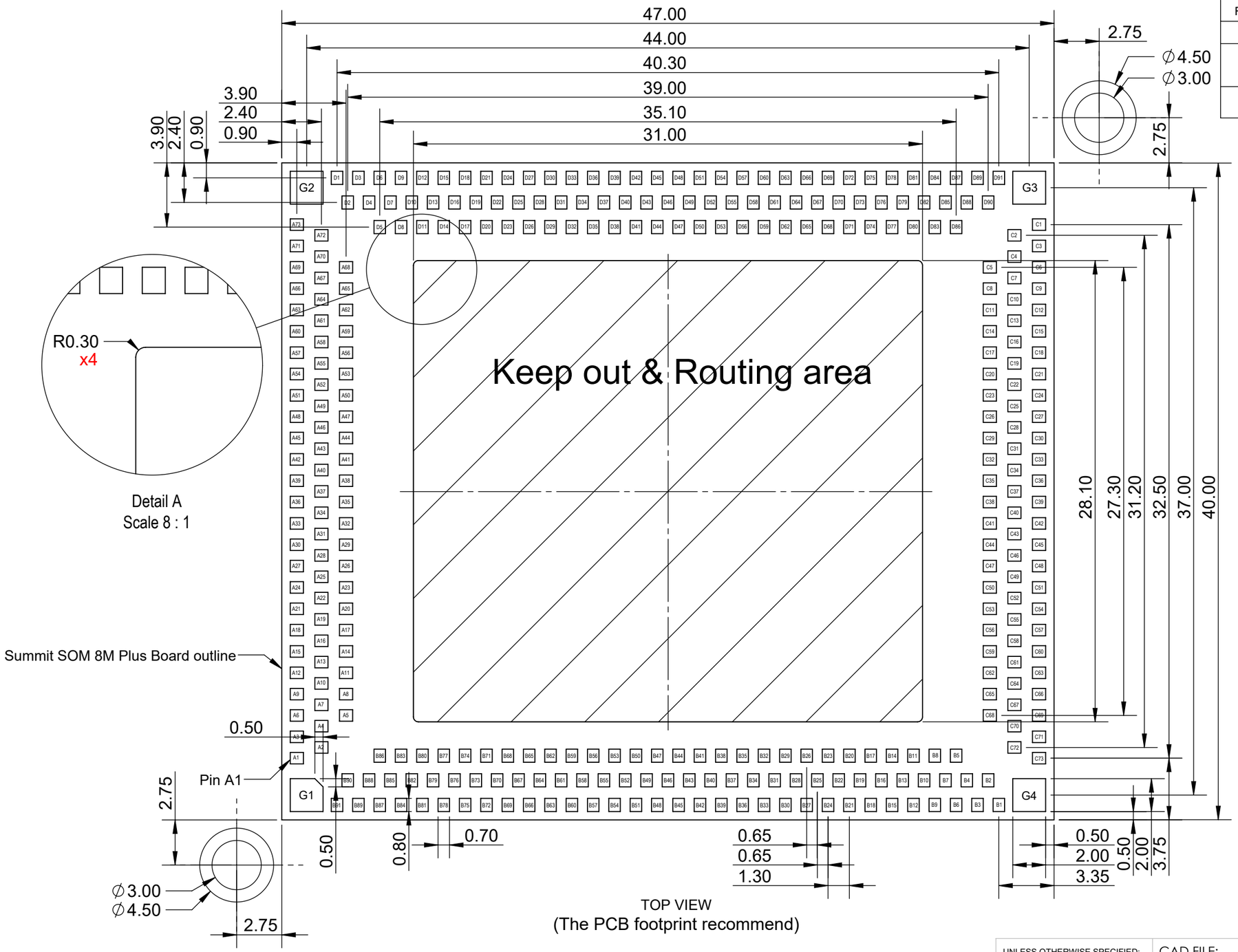
REVISIONS			
REV.	DESCRIPTION	DATE	APPOVED
1.0	Initial	2020-12-17	AC
2.0	Fix the slight gap in size and PCB footprint rename	Oct 5, 2021	AC
3.0	Add detail A and heat sink positioning hole	Dec 21, 2021	AC



Unit:mm

Laird CONNECTIVITY

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES:
ANGULAR: ± - -
X.X ± - -
X.XX ± - -
INTERPRET GEOMETRIC TOLERANCING PER: ASME 14.5M

CAD FILE: Summit SOM 8M Plus_PCB_Footprint

TITLE: **Summit SOM 8M Plus_PCB_Footprint**

DATE Dec 21, 2021

SHEET 1 OF 1 | SCALE: 4:1

SIZE	DWG. NO.	REV
B	- -	3.0

THIRD ANGLE PROJECTION

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